

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>John S. Guzek</td> <td>09/23/2010</td> </tr> <tr> <td>Ravi K. Nalla</td> <td>12/02/2010</td> </tr> <tr> <td>Javier Soto Gonzalez</td> <td>09/24/2010</td> </tr> <tr> <td>Drew Delaney</td> <td>09/24/2010</td> </tr> <tr> <td>Suresh Pothukuchi</td> <td>09/23/2010</td> </tr> <tr> <td>Mohit Mamodia</td> <td>09/23/2010</td> </tr> <tr> <td>Edward Zarbock</td> <td>09/23/2010</td> </tr> <tr> <td>Johanna M. Swan</td> <td>09/23/2010</td> </tr> </tbody> </table>		Name	Execution Date	John S. Guzek	09/23/2010	Ravi K. Nalla	12/02/2010	Javier Soto Gonzalez	09/24/2010	Drew Delaney	09/24/2010	Suresh Pothukuchi	09/23/2010	Mohit Mamodia	09/23/2010	Edward Zarbock	09/23/2010	Johanna M. Swan	09/23/2010
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RECEIVING PARTY DATA																			
<table border="1"> <tr> <td>Name:</td> <td>Intel Corporation</td> </tr> <tr> <td>Street Address:</td> <td>2200 Mission College Blvd.</td> </tr> <tr> <td>City:</td> <td>Santa Clara</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>95052</td> </tr> </table>		Name:	Intel Corporation	Street Address:	2200 Mission College Blvd.	City:	Santa Clara	State/Country:	CALIFORNIA	Postal Code:	95052								
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Application Number:	12890082																		
CORRESPONDENCE DATA																			
Fax Number:	(612)332-8352																		
Phone:	480-715-0970																		
Email:	docketing@cpaglobal.com																		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>																			
Correspondent Name:	Intel Corporation																		
Address Line 1:	c/o CPA Global																		
Address Line 2:	PO Box 52050																		
Address Line 4:	Minneapolis, MINNESOTA 55402																		

CH \$40.00 12890082

PATENT

ATTORNEY DOCKET NUMBER:	P32890
NAME OF SUBMITTER:	John N. Greaves
<p>Total Attachments: 6</p> <p>source=P32890_Executed Assignment#page1.tif</p> <p>source=P32890_Executed Assignment#page2.tif</p> <p>source=P32890_Executed Assignment#page3.tif</p> <p>source=P32890_Executed Assignment#page4.tif</p> <p>source=P32890_Executed Assignment#page5.tif</p> <p>source=P32890_Executed Assignment#page6.tif</p>	

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**JOHN S. GUZEK; RAVI K. NALLA; JAVIER SOTO GONZALEZ; DREW DELANEY;
SURESH POTHUKUCHI; MOHIT MAMODIA; EDWARD ZARBOCK;
JOHANNA M. SWAN**

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

DIE-STACKING USING THROUGH-SILICON VIAS ON BUMPLESS BUILD-UP LAYER SUBSTRATES INCLUDING EMBEDDED-DICE, AND PROCESSES OF FORMING SAME

(I hereby authorize and request my attorney, associated with Customer Number 59796, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on September 24, 2010 as
United States Application Number 12/890,082 and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

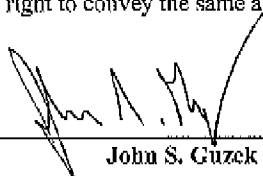
agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the

**INTEL CORPORATION
LCA/PAL FORMS**

Attorney Docket No.: P32890

undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



John S. Guzek

9/23/10
(Today's Date)

Ravi K. Nalla

(Today's Date)

Javier Soto Gonzalez

(Today's Date)

Drew Delaney

(Today's Date)

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John S. Guzek (Today's Date)

N. Ravi Kiran
Ravi K. Nalla 12/02/10
(Today's Date)

Javier Soto Gonzalez (Today's Date)

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John S. Guzek (Today's Date)

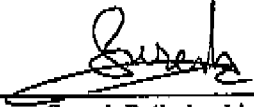
Ravi K. Nalla (Today's Date)




Javier Soto Gonzalez 9/24/10
(Today's Date)



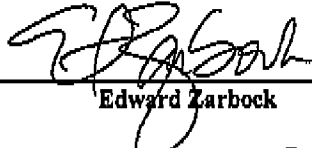
Drew Delaney 9/24/2010
(Today's Date)



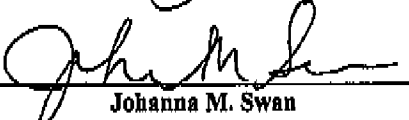
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Edward Zarbock 9/23/10
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Johanna M. Swan 9/23/10
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